Jiashen Du

Curriculum Vitae

 $\label{eq:dujsh2022} $$ \ar{https://alt-js.github.io/dujsh2022@shanghaitech.edu.cn-jason_du@berkeley.edu-(+1)510-918-4582-https://alt-js.github.io/dujsh2022@shanghaitech.edu.cn-jason_du@berkeley.edu-(+1)510-918-4582-https://alt-js.github.io/dujsh2022@shanghaitech.edu.cn-jason_du@berkeley.edu-(+1)510-918-4582-https://alt-js.github.io/dujsh2022@shanghaitech.edu.cn-jason_du@berkeley.edu-(+1)510-918-4582-https://alt-js.github.io/dujsh2022@shanghaitech.edu.cn-jason_du@berkeley.edu-(+1)510-918-4582-https://alt-js.github.io/dujsh2022@shanghaitech.edu.cn-jason_du@berkeley.edu-(+1)510-918-4582-https://alt-js.github.io/dujsh2022@shanghaitech.edu.cn-jason_dujsh2022@shanghaitech.$

EDUCATION

University of California, Berkeley, Berkeley, CA

2024.08 - 2025.05 (Expected)

Junior Exchange student, Computer Science

- Related courses: LLM Agents, Artificial Intelligence, Extended Reality Club DeCal, Introduction to Computer Vision and Computational Photography

ShanghaiTech University, Shanghai, China

2022.09 - 2026.06 (Expected)

Junior, Computer Science

- Total GPA: 3.35/4.0 - TOEFL: 107/120

- Related courses: Introduction to Machine Learning (final project scored 100/100)

RESEARCH AND WORK EXPERIENCE

VRVC Lab, Frontier Base, Shanghai Tech University — 2023.02 - Present

Undergraduate Research Intern — Shanghai, China

Highly involved in the work of the subject group, conducting and participating in research related to 3D Human-Object-Interaction reconstructions. Previous work has been accepted by CVPR 2024 and mainly focuses on fusing LLMs with traditional computer vision methods now.

Guided a high school student to attend China Youth Science and Creativity Contest.

PUBLICATIONS

Conference Proceedings

I'M HOI: Inertia-aware Monocular Capture of 3D Human-Object Interactions

Chengfeng Zhao, Juze Zhang, **Jiashen Du**, Ziwei Shan, Junye Wang, Jingyi Yu, Jingya Wang, Lan Xu. arXiv preprint arXiv:2312.08869. Now accepted by The IEEE/CVF Conference on Computer Vision and Pattern Recognition(CVPR). 2024

AWARDS AND HONORS

CUMCM: Chinese University Mathematical Contest in Modeling

The third prize Year: 2023

ACTIVITIES AND SKILLS

ACTIVITIES

President of ShanghaiTech HiFi Research Club — 2023.05 - Present

Organized events and club activities, such as going to the audio expos. Designing special amplifiers and leading club members to finish annual projects like replicating discontinued HiFi products and making electrostatic headphones. Being invited to host a lecture about headphone and IEM design at the school technology festival.

SKILLS

 $\textbf{Programming Skills:} \ \ \text{Python}(\text{Proficient}), \ C++(\text{Competent}), \ C(\text{Competent}), \ \text{Rust}(\text{Familiar with})$

Language Skills: English(Fluent), Chinese(Native)

Other skills: PCB routing(Familiar with), 3D printing(Familiar with)